

P-channel -30 V, 0.01 Ω typ., -52 A, STripFET™ H6 Power MOSFET in TO-220 package

Datasheet - production data

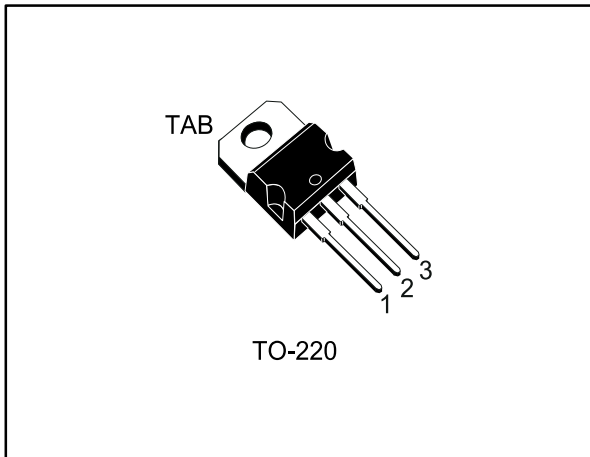
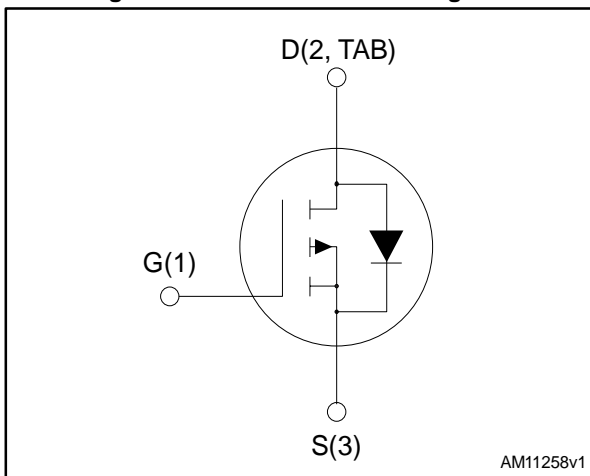


Figure 1: Internal schematic diagram



Order codes	V _{DSS}	R _{DS(on)} max	I _D	P _{TOT}
STP52P3LLH6	-30 V	0.012 Ω	-52 A	70 W

- Very low on-resistance
- Very low gate charge
- High avalanche
- Low gate drive power loss

Applications

- Switching applications

Description

This device is a P-channel Power MOSFET developed using the STripFET™ H6 technology with a new trench gate structure. The resulting Power MOSFET exhibits very low R_{DS(on)} in all packages.

Features

Table 1: Device summary

Order codes	Marking	Package	Packaging
STP52P3LLH6	52P3LLH6	TO-220	Tube

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1 Electrical ratings

Table 2: Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{DS}	Drain-source voltage	-30	V
V_{GS}	Gate-source voltage	± 20	V
I_D	Drain current (continuous) at $T_C = 25\text{ }^\circ\text{C}$	-52	A
I_D	Drain current (continuous) at $T_C = 100\text{ }^\circ\text{C}$	-37.5	A
$I_{DM}^{(1)}$	Drain current (pulsed)	-208	A
P_{TOT}	Total dissipation at $T_C = 25\text{ }^\circ\text{C}$	70	W
T_{stg}	Storage temperature	-55 to 175	$^\circ\text{C}$
T_j	Max. operating junction temperature	175	$^\circ\text{C}$

Notes:

⁽¹⁾Pulse width limited by safe operating area.

Table 3: Thermal data

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Thermal resistance junction-case max	2.14	$^\circ\text{C/W}$
$R_{thj-amb}$	Thermal resistance junction-ambient max	62.5	$^\circ\text{C/W}$

2 Electrical characteristics

(T_{CASE} = 25 °C unless otherwise specified)

Table 4: Static

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V _{(BR)DSS}	Drain-source breakdown Voltage	I _D = -250 μA, V _{GS} = 0	-30			V
I _{DSS}	Zero gate voltage drain current	V _{GS} = 0, V _{DS} = -30 V			-1	μA
		V _{GS} = 0, V _{DS} = -30 V, T _C = 125 °C			-10	μA
I _{GSS}	Gate body leakage current	V _{GS} = ± 20 V, V _{DS} = 0			±100	nA
V _{GS(th)}	Gate threshold voltage	V _{DS} = V _{GS} , I _D = -250 μA	-1		-2.5	V
R _{DS(on)}	Static drain-source on-resistance	V _{GS} = -10 V, I _D = -26 A		0.01	0.012	Ω
		V _{GS} = -4.5 V, I _D = -26 A		0.014	0.017	Ω

Table 5: Dynamic

Symbol	Parameter	Test conditions	Min	Typ.	Max.	Unit
C _{iss}	Input capacitance	V _{DS} = -25 V, f = 1 MHz, V _{GS} = 0	-	3350	-	pF
C _{oss}	Output capacitance		-	414	-	pF
C _{rss}	Reverse transfer capacitance		-	287	-	pF
Q _g	Total gate charge	V _{DD} = -15 V, I _D = -52 A	-	33	-	nC
Q _{gs}	Gate-source charge	V _{GS} = -4.5 V	-	14	-	nC
Q _{gd}	Gate-drain charge	(see Figure 14: "Gate charge test circuit")	-	11	-	nC
R _g	Gate input resistance	I _D = 0 Gate bias = 0 Test signal level = 20 mV; f = 1MHz	-	1.5	-	Ω

Table 6: Switching on/off (inductive load)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
t _{d(on)}	Turn-on delay time	V _{DD} = -24 V, I _D = -15 A, R _G = 4.7 Ω, V _{GS} = -10 V (see Figure 13: "Switching times test circuit for resistive load")	-	12.8	-	ns
t _r	Rise time		-	112	-	ns
t _{d(off)}	Turn-off delay time		-	61	-	ns
t _f	Fall time		-	45	-	ns

Table 7: Source drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{SD}^{(1)}$	Forward on voltage	$I_{SD} = -52 \text{ A}$, $V_{GS} = 0$	-		-1.1	V
t_{rr}	Reverse recovery time	$I_{SD} = -52 \text{ A}$, $di/dt = 100 \text{ A}/\mu\text{s}$, $V_{DD} = -24 \text{ V}$ (see Figure 15: "Test circuit for inductive load switching and diode recovery times")	-	25.2		ns
Q_{rr}	Reverse recovery charge		-	17.4		nC
I_{RRM}	Reverse recovery current		-	-1.4		A

Notes:

⁽¹⁾Pulsed: pulse duration = 300 μs , duty cycle 1.5%

2.1 Electrical characteristics (curves)

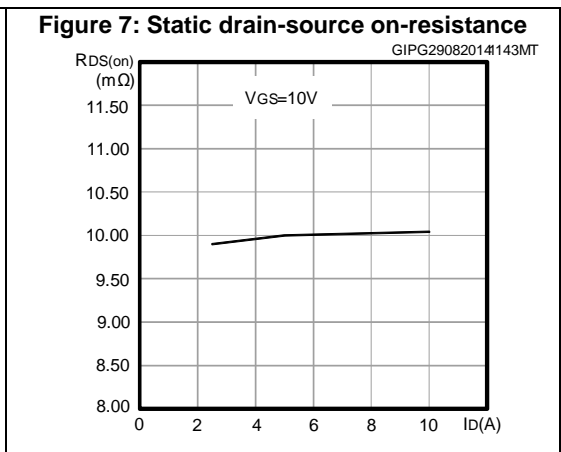
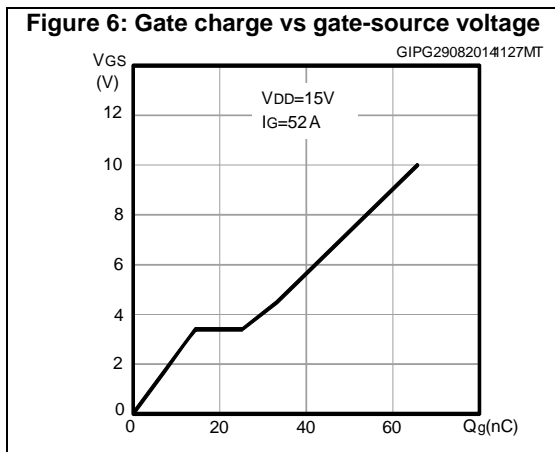
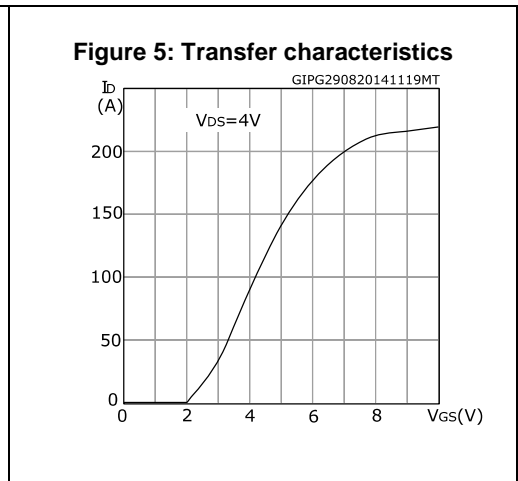
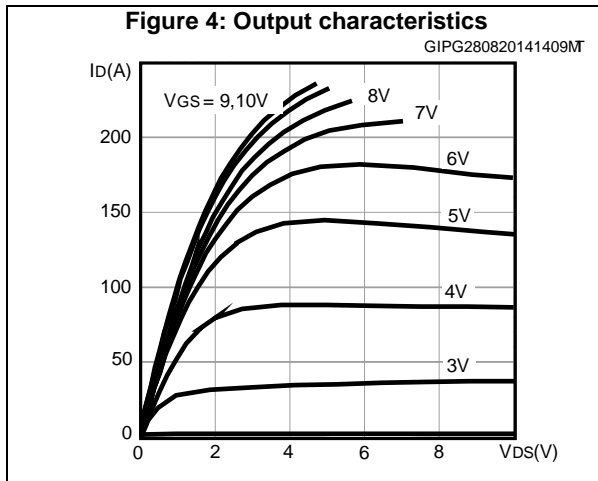
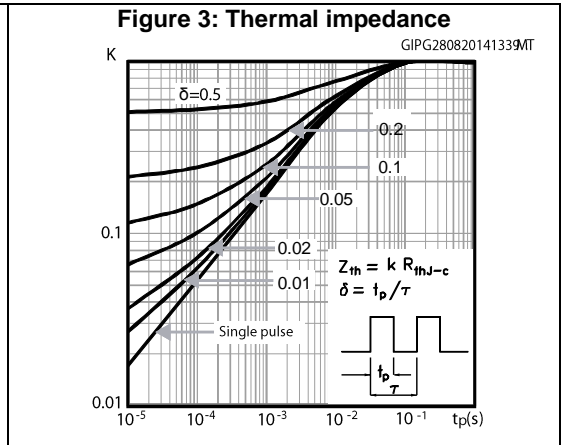
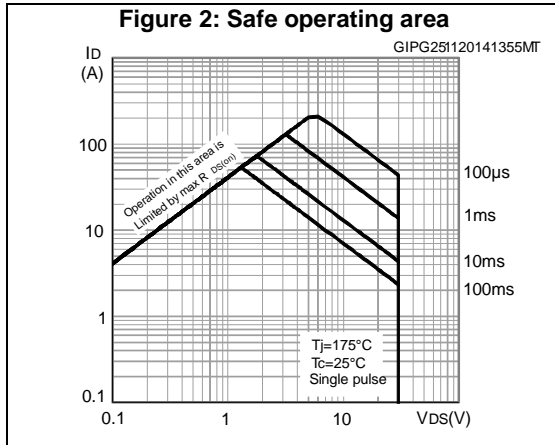


Figure 8: Capacitance variations

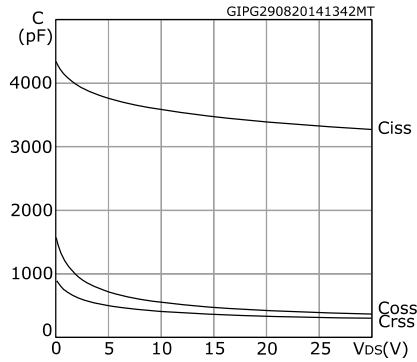


Figure 9: Normalized gate threshold voltage vs temperature

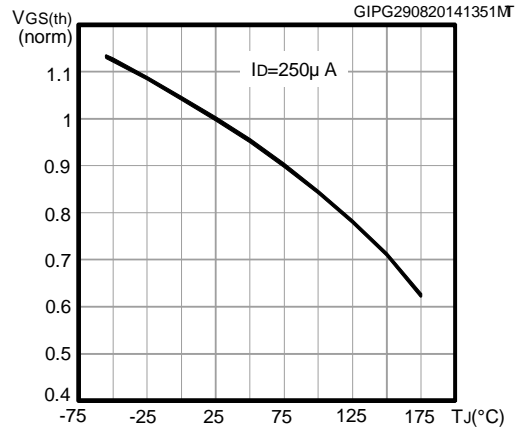


Figure 10: Normalized on-resistance vs temperature

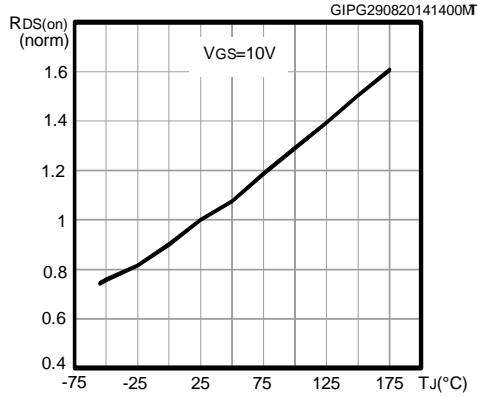


Figure 11: Normalized V(BR)DSS vs temperature

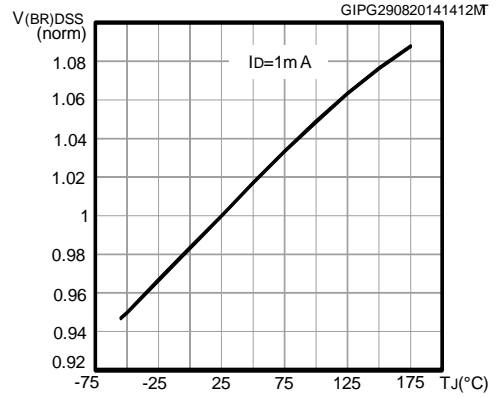
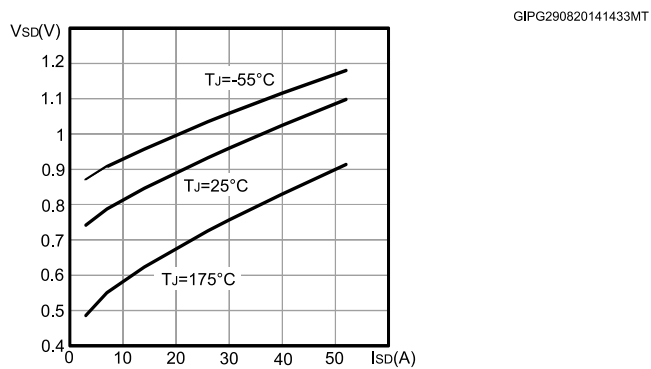


Figure 12: Source-drain diode forward characteristics



For the P-channel Power MOSFET, current and voltage polarities are reversed.

3 Test circuits

Figure 13: Switching times test circuit for resistive load

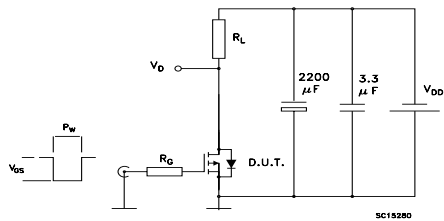


Figure 14: Gate charge test circuit

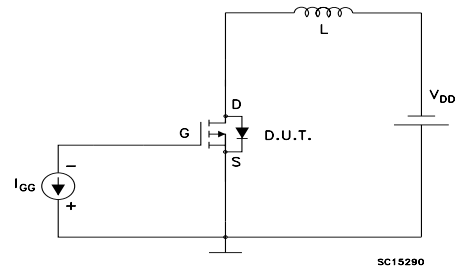
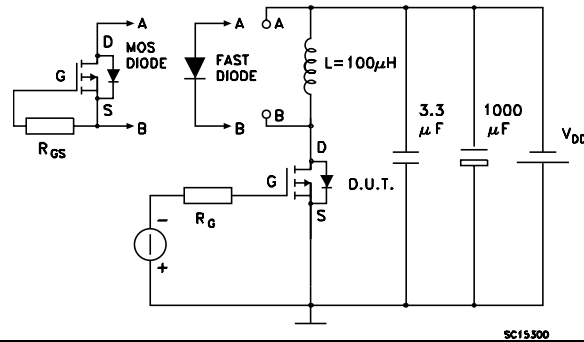


Figure 15: Test circuit for inductive load switching and diode recovery times

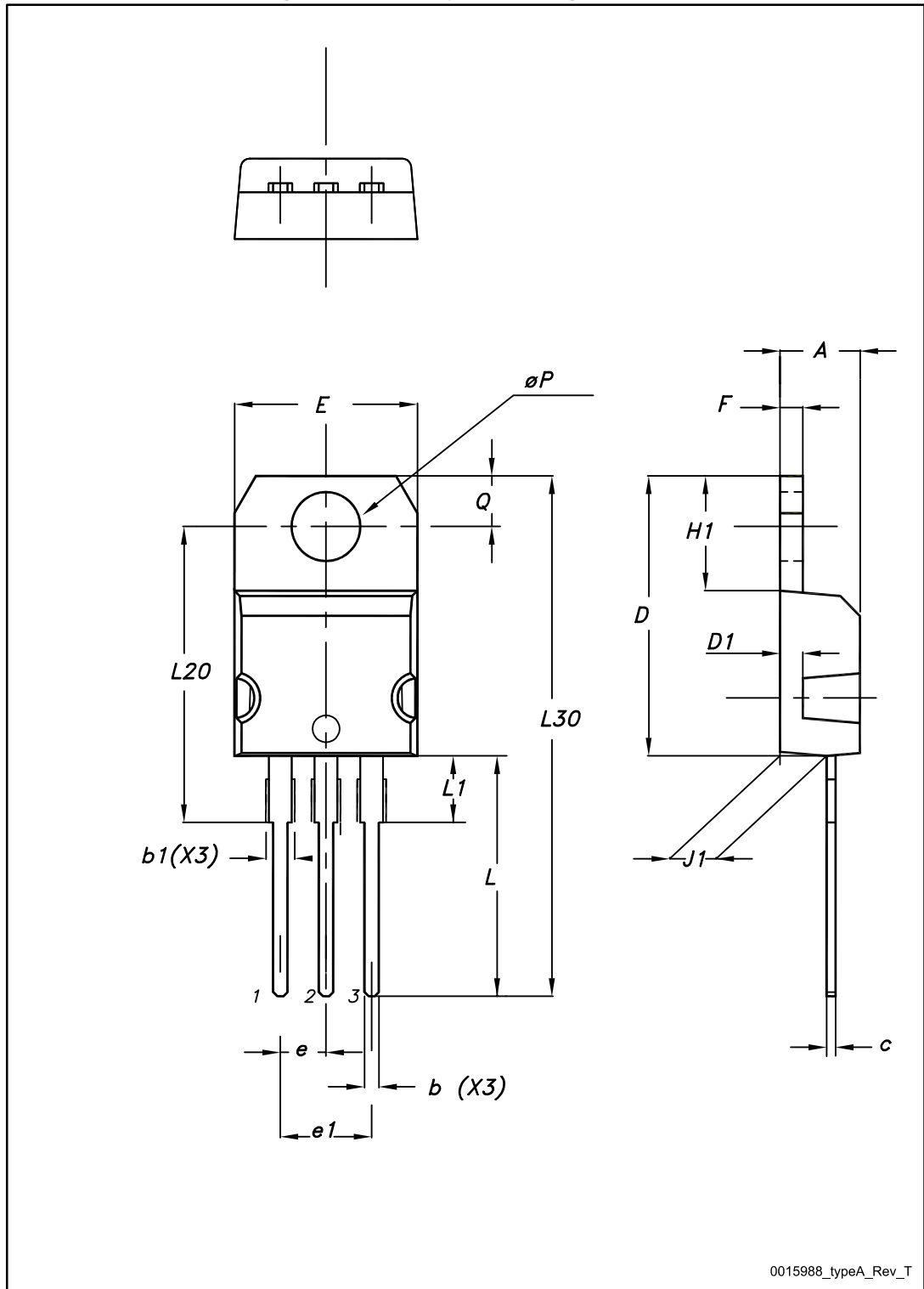


4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

4.1 TO-220 package information

Figure 16: TO-220 type A package outline



0015988_typeA_Rev_T

Table 8: TO-220 type A mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
b	0.61		0.88
b1	1.14		1.70
c	0.48		0.70
D	15.25		15.75
D1		1.27	
E	10		10.40
e	2.40		2.70
e1	4.95		5.15
F	1.23		1.32
H1	6.20		6.60
J1	2.40		2.72
L	13		14
L1	3.50		3.93
L20		16.40	
L30		28.90	
øP	3.75		3.85
Q	2.65		2.95

5 Revision history

Table 9: Document revision history

Date	Revision	Changes
24-Nov-2014	1	First release.
12-Oct-2015	2	Document status promoted from preliminary to production data. Minor text changes.

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